

Lead (Pb)-Free Thick Film, Rectangular Chip Resistors



FEATURES

- Stability $\Delta R/R = 1\%$ for 1000 h at 70 °C
- Pure tin solder contacts on Ni barrier layer provides compatibility with lead (Pb)-free and lead containing soldering processes
- Metal glaze on high quality ceramic
- Compliant to RoHS Directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition
- AEC-Q200 qualified, rev. C compliant



RoHS
COMPLIANT
HALOGEN
FREE

STANDARD ELECTRICAL SPECIFICATIONS								
MODEL	SIZE		RATED DISIPATION $P_{70^\circ\text{C}}$ W	LIMITING ELEMENT VOLTAGE $U_{\text{max. AC/DC}}$	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	SERIES
	INCH	METRIC						
CRCW0201	0201	RR 0603M	0.05	30	± 100 ± 200	± 1 ± 1 ± 5	47R to 1M0	E24; E96
							10R to 1M0	E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 50\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 1.0 A								
D10/CRCW0402	0402	RR 1005M	0.063	50	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 1.5 A								
D11/CRCW0603	0603	RR 1608M	0.10	75	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 2.0 A								
D12/CRCW0805	0805	RR 2012M	0.125	150	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 2.5 A								
D25/CRCW1206	1206	RR 3216M	0.25	200	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 3.5 A								
CRCW1210	1210	RR 3225M	0.5	200	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 5.0 A								
CRCW1218	1218	RR 3246M	1.0	200	± 100 ± 200	± 1 ± 5	1R0 to 2M2	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 7.0 A								
CRCW2010	2010	RR 5025M	0.75	400	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 6.0 A								
CRCW2512	2512	RR 6332M	1.0	500	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96
								E24
Zero-Ohm-Resistor: $R_{\text{max.}} = 20\text{ m}\Omega$, $I_{\text{max.}}$ at 70 °C = 7.0 A								

Notes

- These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.
- Marking: See data sheet "Surface Mount Resistor Marking" (document number 20020).
- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material.



TECHNICAL SPECIFICATIONS										
PARAMETER	UNIT	CRCW0201	D10/ CRCW0402	D11/ CRCW0603	D12/ CRCW0805	D25/ CRCW1206	CRCW1210	CRCW1218	CRCW2010	CRCW2512
Rated dissipation P_{70} ⁽¹⁾	W	0.05	0.063	0.1	0.125	0.25	0.5	1.0	0.75	1.0
Limiting element voltage U_{max} AC/DC	V	30	50	75	150	200	200	200	400	500
Insulation voltage U_{ins} (1 min)	V	50	> 75	> 100	> 200	> 300	> 300	> 300	> 300	> 300
Insulation resistance	Ω	> 10^9								
Category temperature range	$^{\circ}\text{C}$	- 55 to + 155								
Failure rate	h^{-1}	1×10^{-9}	< 0.1×10^{-9}							
Weight	mg	0.17	0.65	2	5.5	10	16	29.5	25.5	40.5

Note

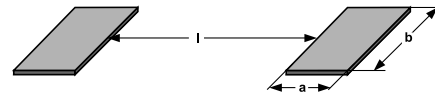
⁽¹⁾ The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.

PART NUMBER AND PRODUCT DESCRIPTION																	
Part Number: CRCW0603562RFKEC ⁽²⁾																	
C	R	C	W	0	6	0	3	5	6	2	R	F	K	E	C		
MODEL	VALUE	TOLERANCE	TCR	PACKAGING	SPECIAL												
CRCW0201 CRCW0402 CRCW0603 CRCW0805 CRCW1206 CRCW1210 CRCW1218 CRCW2010 CRCW2512	R = Decimal K = Thousand M = Million 0000 = Jumper	F = ± 1.0 % J = ± 5.0 % Z = Jumper	K = ± 100 ppm/K N = ± 200 ppm/K 0 = Jumper S = Special	EA, EB, EC, ED, EE, EF, EG, EH, EK	Up to 2 digits												
Product Description: D11/CRCW0603 100 562R 1 % ET6 e3																	
D11/CRCW0603	100	562R	1 %	ET6	e3												
MODEL	TCR	RESISTANCE VALUE	TOLERANCE	PACKAGING	LEAD (Pb)-FREE												
CRCW0201 D10/CRCW0402 D11/CRCW0603 D12/CRCW0805 D25/CRCW1206 CRCW1210 CRCW1218 CRCW2010 CRCW2512	± 200 ppm/K ± 100 ppm/K	10R = 10 Ω 562R = 562 Ω 10K = 10 k Ω 1M = 1 M Ω 0R0 = Jumper	± 5 % ± 1 %	ET1, ET5, ET6, ET7, EF4, E02, E67, E82, ET9	e3 = Pure tin termination finish												

Note

⁽²⁾ Preferred way for ordering products is by use of the PART NUMBER.

PACKAGING							
MODEL	UNIT	PAPER TAPE ON REEL ACC. TO IEC 60286-3, TYPE I			BLISTER TAPE ON REEL ACC. TO IEC 60286-3, TYPE II		
		QUANTITY	PART NUMBER	PRODUCT DESC.	QUANTITY	PART NUMBER	PRODUCT DESC.
CRCW0201	180 mm/7"	10 000	ED	ET7			
	330 mm/13"	50 000	EE	EF4			
D10/CRCW0402	180 mm/7"	10 000	ED	ET7			
	330 mm/13"	50 000	EE	EF4			
D11/CRCW0603	180 mm/7"	5000	EA	ET1			
	285 mm/11.25"	10 000	EB	ET5			
	330 mm/13"	20 000	EC	ET6			
D12/CRCW0805	180 mm/7"	5000	EA	ET1			
	285 mm/11.25"	10 000	EB	ET5			
	330 mm/13"	20 000	EC	ET6			
D25/CRCW1206	180 mm/7"	5000	EA	ET1			
	285 mm/11.25"	10 000	EB	ET5			
	330 mm/13"	20 000	EC	ET6			
CRCW1210	180 mm/7"	5000	EA	ET1			
	285 mm/11.25"	10 000	EB	ET5			
	330 mm/13"	20 000	EC	ET6			
CRCW1218	180 mm/7"				4000	EK	ET9
CRCW2010	180 mm/7"				4000	EF	E02
CRCW2512	180 mm/7"				2000	EG	E67
					4000	EH	E82

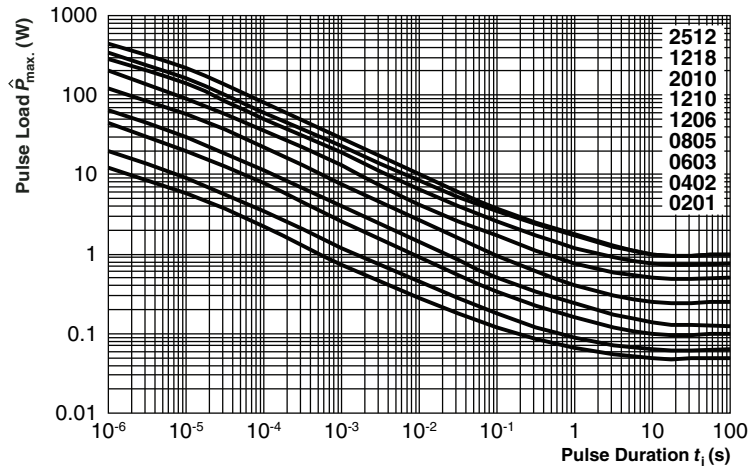
DIMENSIONS


SIZE		DIMENSIONS in millimeters					SOLDER PAD DIMENSIONS in millimeters					
							REFLOW SOLDERING			WAVE SOLDERING		
INCH	METRIC	L	W	H	T1	T2	a	b	l	a	b	l
0201	0525	0.6 ± 0.05	0.3 ± 0.05	0.23 ± 0.05	0.15 ± 0.05	0.15 ^{+0.05} / _{-0.10}	0.28	0.43	0.23			
0402	1005	1.0 ± 0.05	0.5 ± 0.05	0.35 ± 0.05	0.25 ± 0.05	0.2 ± 0.1	0.4	0.6	0.5			
0603	1608	1.55 ^{+0.10} / _{-0.05}	0.85 ± 0.1	0.45 ± 0.05	0.3 ± 0.2	0.3 ± 0.2	0.5	0.9	1.0	0.9	0.9	1.0
0805	2012	2.0 ^{+0.20} / _{-0.10}	1.25 ± 0.15	0.45 ± 0.05	0.3 ^{+0.20} / _{-0.10}	0.3 ± 0.2	0.7	1.3	1.2	0.9	1.3	1.3
1206	3216	3.2 ^{+0.10} / _{-0.20}	1.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	1.7	2.0	1.1	1.7	2.3
1210	3225	3.2 ± 0.2	2.5 ± 0.2	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	2.5	2.0	1.1	2.5	2.2
1218	3246	3.2 ^{+0.10} / _{-0.20}	4.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	1.05	4.9	1.9	1.25	4.8	1.9
2010	5025	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	2.5	3.9	1.2	2.5	3.9
2512	6332	6.3 ± 0.2	3.15 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	3.2	5.2	1.2	3.2	5.2



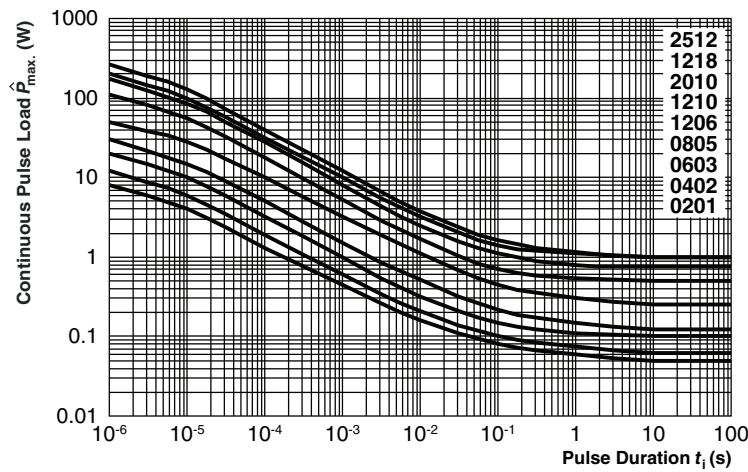
FUNCTIONAL PERFORMANCE

Single Pulse



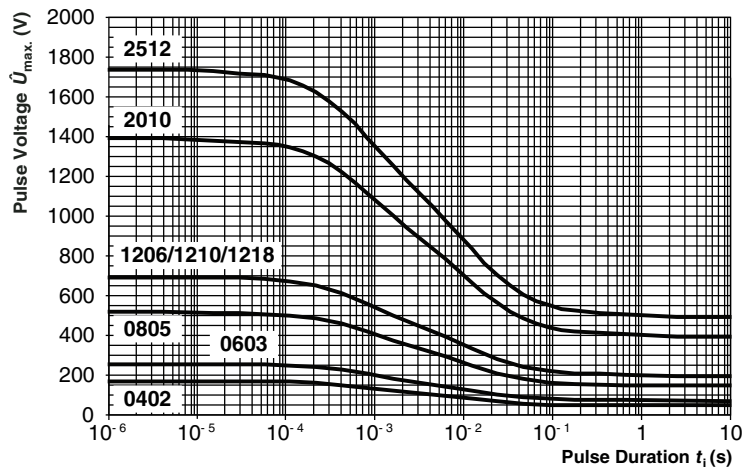
Maximum pulse load, single pulse; applicable if $\bar{P} \rightarrow 0$ and $n < 1000$ and $\bar{U} \leq \bar{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

Continuous Pulse



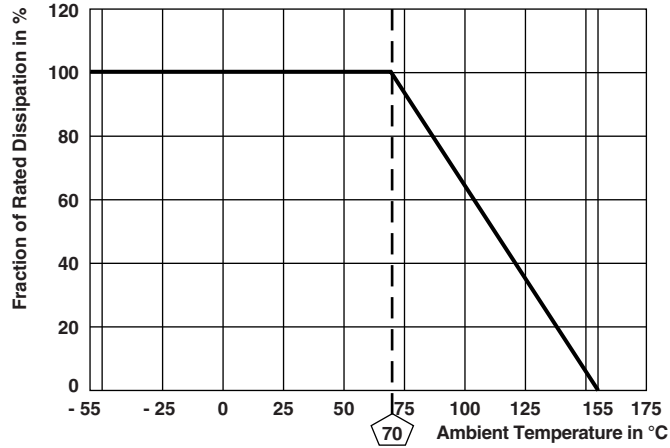
Maximum pulse load, continuous pulses; applicable if $\bar{P} \leq P(9_{amb})$ and $\bar{U} \leq \bar{U}_{max}$; for permissible resistance change equivalent to 8000 h operation

Pulse Voltage



Maximum pulse voltage, single and continuous pulses; applicable if $\hat{P} \leq \hat{P}_{max}$; for permissible resistance change equivalent to 8000 h operation

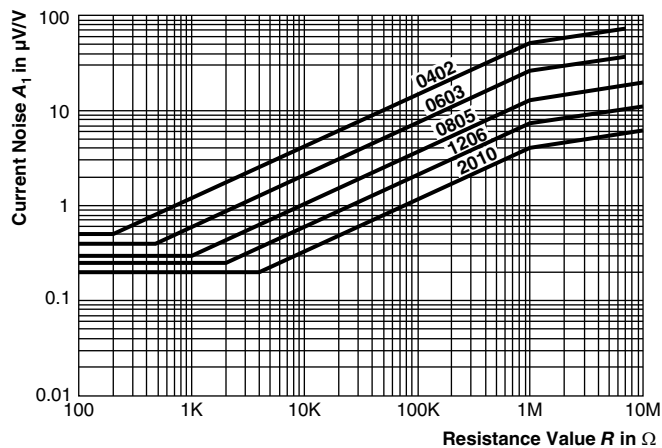
Derating



Non-Linearity



Current Noise



TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)		
				SIZE 0402 to 2512		SIZE 0201
				STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER	REQUIREMENTS PERMISSIBLE CHANGE ($\Delta R/R$)
			Stability for product types:			
			D/CRCW e3	1 Ω to 10 M Ω	1 Ω to 10 M Ω	10 Ω to 1 M Ω
4.5	-	Resistance	-	$\pm 1\%$	$\pm 5\%$	$\pm 1\%$; $\pm 5\%$
4.7	-	Voltage proof	$U = 1.4 \times U_{ins}$; 60 s	No flashover or breakdown		
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70} \times R} \leq 2 \times U_{max.}$; duration: Acc. to style	$\pm (0.25\% R + 0.05 \Omega)$	$\pm (0.5\% R + 0.05 \Omega)$	$\pm (1\% R + 0.05 \Omega)$
4.17.2	58 (Td)	Solderability	Solder bath method; Sn60Pb40 non activated flux; (235 \pm 5) $^{\circ}$ C (2 \pm 0.2) s	Good tinning ($\geq 95\%$ covered) no visible damage		
			Solder bath method; Sn96.5Ag3Cu0.5 non-activated flux; (245 \pm 5) $^{\circ}$ C (3 \pm 0.3) s	Good tinning ($\geq 95\%$ covered) no visible damage		
4.8.4.2	-	Temperature coefficient	(20/- 55/20) $^{\circ}$ C and (20/125/20) $^{\circ}$ C	± 100 ppm/K	± 200 ppm/K	± 100 ppm/K, ± 200 ppm/K
4.32	21 (Uu ₃)	Shear (adhesion)	RR 1608 and smaller: 9 N RR 2012 and larger: 45 N	No visible damage		
4.33	21 (Uu ₁)	Substrate bending	Depth 2 mm; 3 times	No visible damage, no open circuit in bent position $\pm (0.25\% R + 0.05 \Omega)$ $\pm (0.5\% R + 0.05 \Omega)$		
4.19	14 (Na)	Rapid change of temperature	30 min. at - 55 $^{\circ}$ C; 30 min. at 125 $^{\circ}$ C			
			5 cycles 1000 cycles	$\pm (0.25\% R + 0.05 \Omega)$ $\pm (1\% R + 0.05 \Omega)$	$\pm (0.5\% R + 0.05 \Omega)$ $\pm (1\% R + 0.05 \Omega)$	$\pm (0.5\% R + 0.05 \Omega)$ $\pm (1\% R + 0.05 \Omega)$
4.23	-	Climatic sequence:	-			
4.23.2	2 (Ba)	Dry heat	125 $^{\circ}$ C; 16 h			
4.23.3	30 (Db)	Damp heat, cyclic	55 $^{\circ}$ C; $\geq 90\%$ RH; 24 h; 1 cycle			
4.23.4	1 (Aa)	Cold	- 55 $^{\circ}$ C; 2 h	$\pm (1\% R + 0.05 \Omega)$	$\pm (2\% R + 0.1 \Omega)$	$\pm (2\% R + 0.1 \Omega)$
4.23.5	13 (M)	Low air pressure	1 kPa; (25 \pm 10) $^{\circ}$ C; 1 h			
4.23.6	30 (Db)	Damp heat, cyclic	55 $^{\circ}$ C; $\geq 90\%$ RH; 24 h; 5 cycles			
4.23.7	-	DC load	$U = \sqrt{P_{70} \times R}$			
4.25.1	-	Endurance at 70 $^{\circ}$ C	$U = \sqrt{P_{70} \times R} \leq U_{max.}$; 1.5 h on; 0.5 h off;			
			70 $^{\circ}$ C; 1000 h	$\pm (1\% R + 0.05 \Omega)$	$\pm (2\% R + 0.1 \Omega)$	$\pm (2\% R + 0.1 \Omega)$
			70 $^{\circ}$ C; 8000 h	$\pm (2\% R + 0.1 \Omega)$	$\pm (4\% R + 0.1 \Omega)$	$\pm (4\% R + 0.1 \Omega)$

TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)		
				SIZE 0402 to 2512		SIZE 0201
				STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER	REQUIREMENTS PERMISSIBLE CHANGE ($\Delta R/R$)
			Stability for product types:			
			D/CRCW e3	1 Ω to 10 M Ω	1 Ω to 10 M Ω	10 Ω to 1 M Ω
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 \pm 5) $^{\circ}$ C; (10 \pm 1) s	\pm (0.25 % R + 0.05 Ω)	\pm (0.5 % R + 0.05 Ω)	\pm (1 % R + 0.05 Ω)
4.35	-	Flamability, needle flame test	IEC 60695-11-5; 10 s	No burning after 30 s		
4.24	78 (Cab)	Damp heat, steady state	(40 \pm 2) $^{\circ}$ C; (93 \pm 3) % RH; 56 days	\pm (1 % R + 0.05 Ω)		\pm (2 % R + 0.1 Ω)
4.25.3	-	Endurance at upper category temperature	155 $^{\circ}$ C, 1000 h	\pm (1 % R + 0.05 Ω)	\pm (2 % R + 0.1 Ω)	\pm (2 % R + 0.1 Ω)
4.40	-	Electrostatic discharge (human body model)	IEC 61340-3-1; 3 pos. + 3 neg. discharges; ESD voltage acc. to size	\pm (1 % R + 0.05 Ω)		
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 $^{\circ}$ C; method 2	No visible damage		
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 $^{\circ}$ C; method 1, toothbrush	Marking legible, no visible damage		
4.22	6 (Fc)	Vibration, endurance by sweeping	f = 10 Hz to 2000 Hz; x, y, z \leq 1.5 mm; A \leq 200 m/s ² ; 10 sweeps per axis	\pm (0.25 % R + 0.05 Ω)	\pm (0.5 % R + 0.05 Ω)	\pm (0.5 % R + 0.05 Ω)
4.37	-	Periodic electric overload	$U = \sqrt{15 \times P_{70} \times R}$ $\leq 2 \times U_{max.}$; 0.1 s on; 2.5 s off; 1000 cycles	\pm (1 % R + 0.05 Ω)		
4.27	-	Single pulse high voltage overload, 10 μ s/700 μ s	$\dot{U} = 10 \times \sqrt{P_{70} \times R}$ $\leq 2 \times U_{max.}$; 10 pulses	\pm (1 % R + 0.05 Ω)		

All tests are carried out in accordance with the following specifications:

- EN 60115-1, generic specification
- EN 140400, sectional specification
- EN 140401-802, detail specification
- IEC 60068-2, environmental test procedures

Packaging of components is done in paper or blister tapes according to IEC 60286-3.



Disclaimer

All product specifications and data are subject to change without notice.

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